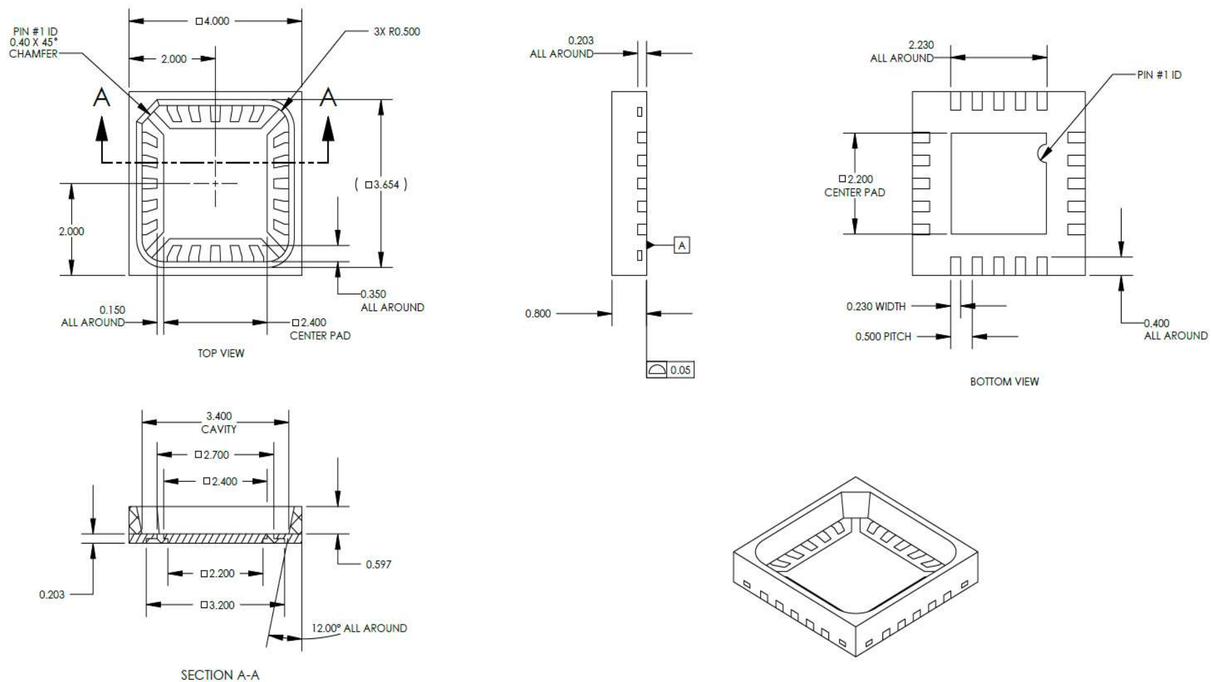
Technical Specifications

1. Package Type: Quad Flat No-Leads Package (QFN) along with Lid, Qty: 100 no's
2. Lead Frame: Copper 194FH, Thickness : 0.203 ± 0.008 mm
3. Body: Plastic Material (Semiconductor Molding Epoxy)
4. Finish: Lead Frame: Electroless Nickel as per MIL-C-26074, Class 1, 100 to 300 micro-inches (2.5um-7.6um) thick. Gold Plate as per MIL-G-45204, Type 3, Grade A, Class 1(40 to 80 micro-inches (1um-2um) thick, Body Surface Finish: VDI 21-24 (1.12-1.6 Ra)
5. Package shape & Size: Square, 4.0 mm x 4.0 mm
6. Package Cavity & Die Mounting area: 3.4 mm Sq & 2.4 mm Sq
7. Number of Pins: 20 pins (Each side 5 pins. Total 4 sides)
8. Quoted package should conform to JEDEC MO-220 standard.
9. Package should be suitable for surface mounting and solder attaching on to the PCB.
10. Vendor should provide the package drawing along with quotation.
11. Vendor has to quote the suitable plastic lids for above QFN package with sealable material around the lid periphery.
12. Package dimensions: As per drawing mentioned.

Typical Package Drawing



All Dimensions are in mm